



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-01-15
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6206QTR	88V0*UF36AJV	A	Calamba - Manila	2016-01-15
Amount		UoM	Unit type	ST ECOPACK Grade
130.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	7, 7, 1	48	NO LEAD	
Comment	VFQFPN 7x7x1.0 48 PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	88V0*UF36AJV					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	11.152	mg	supplier	die	Silicon (Si)	7440-21-3		10.598	mg	950318	81515
				supplier	metallization	Aluminum (Al)	7429-90-5		0.107	mg	9596	823
				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	1076	92
				supplier	Passivation	Silicon Nitride	12033-89-5		0.032	mg	2870	246
				supplier	Passivation	Silicon Oxide	7631-86-9		0.185	mg	16590	1423
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	717	62
				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1973	169
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	6457	554
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.116	mg	10403	892
				Leadframe	Copper & Its alloys	35.690	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.018	mg	504	138
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.028	mg	785	215
supplier	metallization	Nickel (Ni)	7440-02-0						0.223	mg	6248	1715
supplier	metallization	Palladium (Pd)	7440-05-3						0.014	mg	392	108
supplier	metallization	Gold (Au)	7440-57-5						0.006	mg	168	46
Die attach	Other Organic Materials	3.379	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		2.312	mg	684226	17785
				supplier	glue or tape	methylene diacrylate	42594-17-2		0.845	mg	250074	6500
				supplier	glue or tape	Dicyclopentenyl ethyl methacrylate	68586-19-6		0.101	mg	29891	777
				supplier	glue or tape	Polymer of Polybutadiene + Anhydride	Proprietary		0.101	mg	29891	777
				supplier	glue or tape	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.017	mg	5031	131
				supplier	glue or tape	Palladium (Pd)	7440-05-3		0.003	mg	888	23
Bonding wires	Other inorganic materials	0.749	mg	supplier	wire	Gold (Au)	7440-57-5		0.742	mg	990654	5708
				supplier	wire	Palladium (Pd)	7440-05-3		0.007	mg	9346	54
Encapsulation	Other Organic Materials	79.030	mg	supplier	mold compound	silica vitreous	60676-86-0		67.413	mg	853005	518562
				supplier	mold compound	epoxy resin	25068-38-6		3.161	mg	39997	24315
				supplier	mold compound	Phenol resin	29690-82-2		2.766	mg	34999	21277
				supplier	mold compound	Magnesium hydroxide	1309-42-8		3.161	mg	39997	24315
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		1.581	mg	20005	12162
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.790	mg	9996	6077
				supplier	mold compound	carbon black	1333-86-4		0.158	mg	1999	1215